CHIPQUIK® RASW.031 8OZ

Datasheet revision 1.1 www.chipquik.com

Solder Wire Sn63/Pb37 Rosin Activated with 2.0% Flux Core 8oz Spool

Product Highlights

RA (Rosin Activated)
2.0% Flux Core
A stronger activated flux for hard to solder surfaces

Specifications

Alloy:	Sn63/Pb37
Wire Diameter:	0.031” (0.8mm)
Flux Type:	Rosin Activated
Flux Classification:	ROM0
Melting Point:	183°C (361°F)
Packaging:	8oz spool
Shelf Life:	>60 months

Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	M: Slight corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.05%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains Lead (Pb) CAS# 7439-92-1 No other SVHC present

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 3 Directive (EU) 2015/863:	No

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